

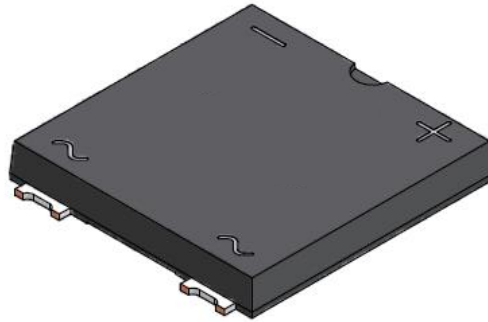
TSB302 thru TSB307

low Profile Surface Mount Single Phase Bridge Rectifiers

Reverse Voltage 100 to 1000V Forward Current 3.0A

FEATURES

- * Low forward voltage drop
- * Low leakage current
- * Ideal for automated placement
- * Glass passivated standard bridge rectifiers
- * Moisture sensitivity: level 1
- * Low profile, Typical Height 1.5mm
- * High temperature soldering guaranteed:
260°C/10 seconds
- * Weight: 0.505g



Typical Applications

For use of general purpose AC to DC bridge rectification in power supply, charger, office appliance, home appliance and telecom device

We declare that the material of product is Halogen free (green epoxy compound)

1. Maximum Ratings at 25°C unless otherwise noted

Parameter Symbol	symbol	TSB302	TSB303	TSB304	TSB305	TSB306	TSB307	Unit
device marking code		TSB302	TSB303	TSB304	TSB305	TSB306	TSB307	
Maximum repetitive peak reverse voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_F(AV)$	3.0						A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	120						A
Rating for fusing (t<8.3ms)	I^2t	60						A ² sec
Typical thermal resistance (Note 1)	$R_{\theta JC}$ $R_{\theta JA}$	12 55						°C/W
Operating junction and storage temperature range	TJ, TSTG	-55 to +150						°C

Electrical Characteristics at 25°C unless otherwise noted

Parameter Symbol	symbol	TSB302	TSB303	TSB304	TSB305	TSB306	TSB307	Unit
Maximum Instantaneous Forward Voltage ($I_F = 1.5$ Amps, $T_J = 25^\circ\text{C}$) ($I_F = 3.0$ Amps, $T_J = 25^\circ\text{C}$)	V_F	0.95 1.05						V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ\text{C}$ $T_A = 125^\circ\text{C}$	I_R	5 250						μA
Typical junction capacitance at 4.0V, 1MHz	CJ	32						PF

NOTES:

1. 64.0cm² (.050mm thick) land areas

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2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

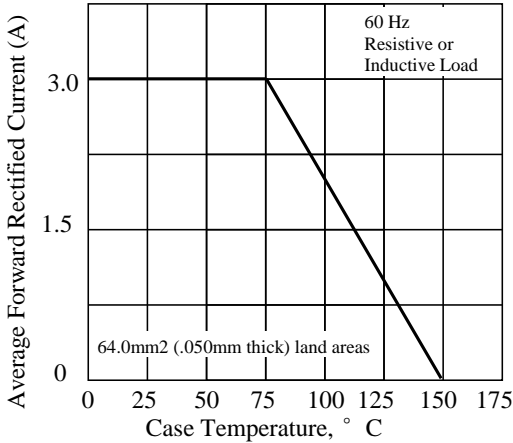


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

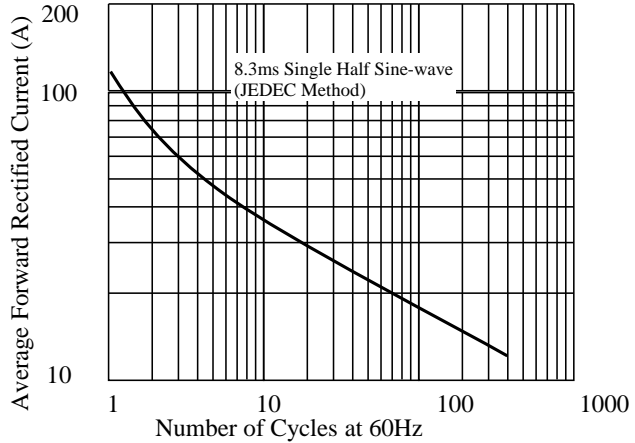


Fig 3. - Typical Instantaneous Forward Characteristics

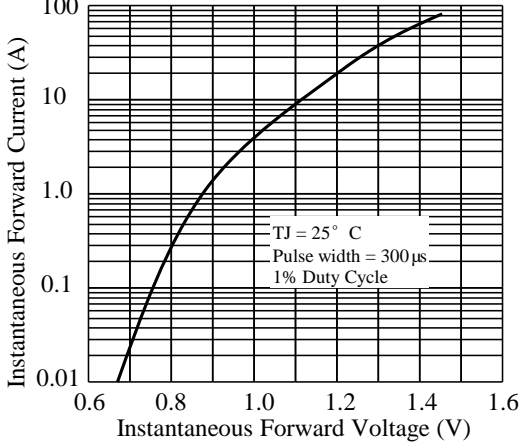


Fig 4. - Typical Reverse Characteristics

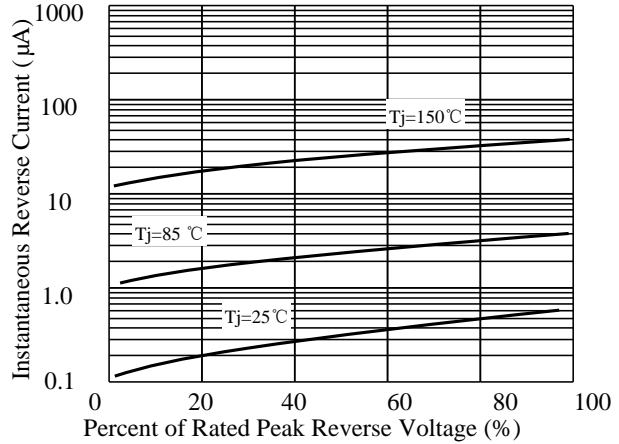


Fig 5. - typical transient thermal impedance

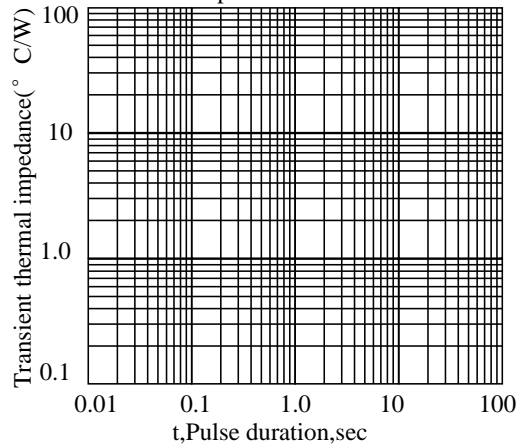
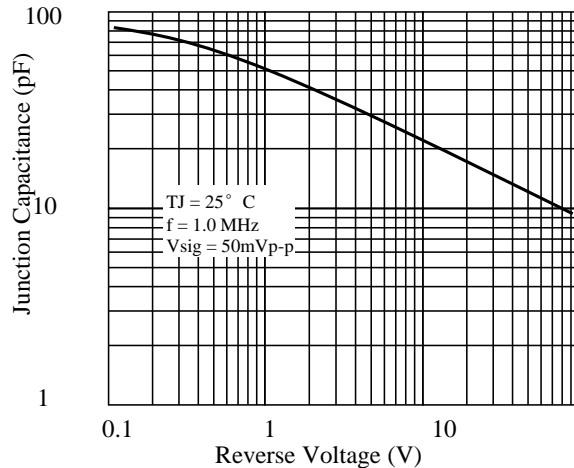


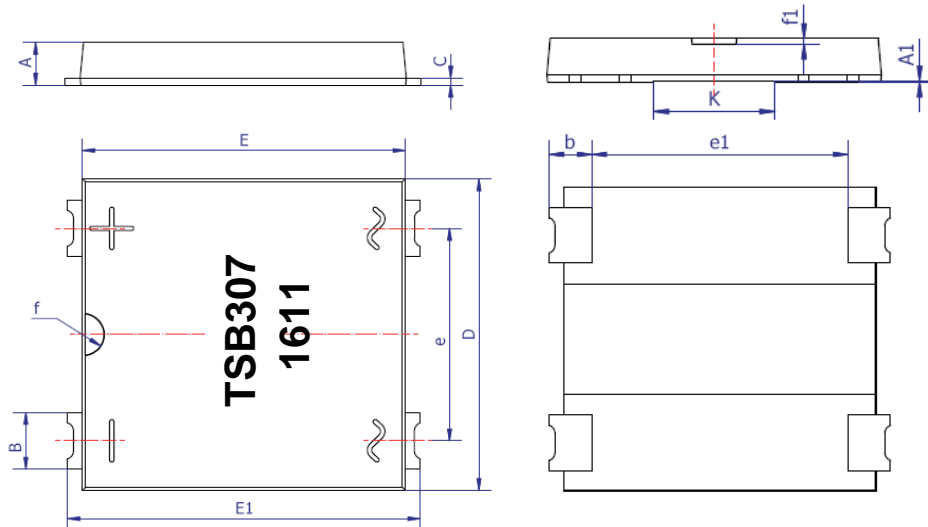
Fig 6. - Typical Junction Capacitance



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3. dimension:

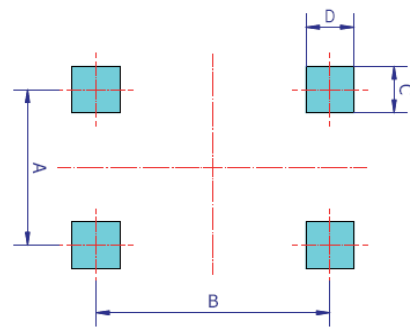
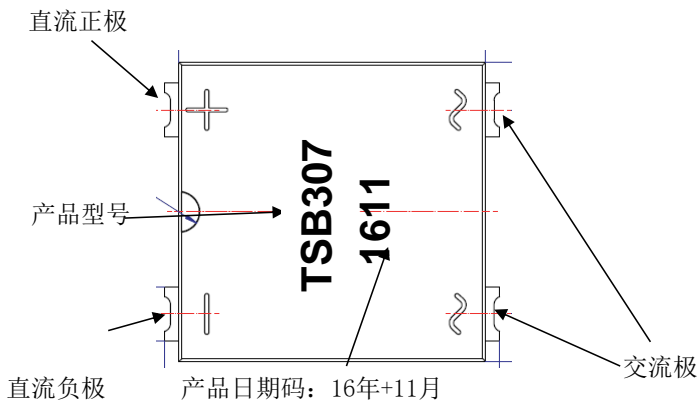
TSB



unit:mm

Dim	MIN	MAX	Dim	MIN	MAX
A	1.40	1.60	f	0.70	0.80
B	1.80	2.20	f1	0.15	0.25
C	0.20	0.30	A1	0.03	0.10
D	10.80	11.20	K	3.80	4.20
E	10.80	11.20	b	1.30	1.70
E1	11.80	12.20	e1	8.80	9.20
e	7.30	7.70			

Mounting PAD layout



产品型号说明: T---薄形; S---贴片; B---桥; 3--IF=3A;07--VR=1000V;

Dim	MIN	MAX
A	7.30	7.70
B	10.25	10.75
C	3.50	4.50
D	3.50	4.50

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4、版式次更新记录

版次	更新记录	更新作者	更新日期
1	第一版	谭志伟	2017. 8. 19